

U.S. Department of Commerce, Patent and Trademark Office	Atty Docket No.	Application No.
SEP 22 2005	M-12524 US	10/056,154
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Applicant(s)	Confirmation No.
Substitute Form PTO 1449	Fortin, Vincent	2279
	Filing Date	Group
	23 January 2002	2823

## U.S. Patent Documents

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA					
	AB					
	AC					
	AD					
	AE					
	AF					
	AG					
	AH					
	AI					
	AJ					
	AK					
	AL					

## Foreign Patent Documents

							Translation	
	Document	Date	Country	Class	Subclass		Yes	No
	AM							
	AN							
	AO							
	AP							
	AQ							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

Le	AR	Hopwood, "Ionized physical vapor deposition of integrated circuit interconnects", <u>Physics of Plasmas</u> , May 1998, pp. 1624 - 1631
Le	AS	"Applied Materials Launches Advanced Cobalt Solution for Nano-Chip Manufacturing", Business Wire, Applied Materials, <a href="http://www.businesswire.com/cgi-bin/cnn-storydisplay.cgi?story=www/between/webboc/bw.1204...1">http://www.businesswire.com/cgi-bin/cnn-storydisplay.cgi?story=www/between/webboc/bw.1204...1</a> , Dec. 4, 2001, 1 page
	AT	

Examiner

Date Considered

11/8/05

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.